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Beroz et al.

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BT	AL	WO 95/34106	12/1995	WIPO						
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BT	AR Andros and Hammer, "TBGA Package Technology" IEEE Transactions on Components, Packaging and Manufacturing Technology, Part B, Vol. 17, No. 4, VP 564-568.									
B	AS	Lau, John H., Ball Grid Array Technology, pp. 460-464.								
Publication, in American National Standard ANSI/IPC-D-249, "Design Standard for Flexible Single and Double Sided Printed Boards," January 1997, p. 47.										
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^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

FORM PTO-14- (Rev. 7-80)	49	U.S. Department of Com Patent and Trademark O						lication No. iv. of 09/277,677	
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135	American National Standard ANSI/IPCD-275 of September 1991 entitled Design Standard for Rigid Printed Boards and Rigid Printed Board Assemblies, pp.62-68.								rinted
B	AS	Design Guidelines for Surface Mount and Fine Pitch Technology, 2nd edition, 1996 by Vernon Solberg, pp.142-143.							
BT	AT	Fjelstad, An Engineer's Guide to Flexible Circuit Technology (ElectroChemical Publications Limited 1997; ISBN 0901150347), pp.148-149.							
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BÍ	AS	IBM Technical Disclosure Bulletin, Vol. 40, No. 6, pp.199-200 entitled "Ball Grid Array Solder Ball on Ball Grid Array Dimple Pad" (June 1997).								
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